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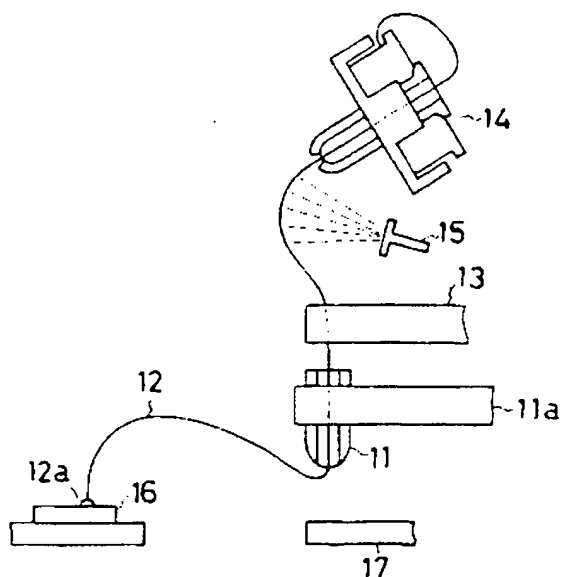
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TITLE : BONDING DEVICE



ABSTRACT : PURPOSE: To remove the slackness at the upper part of the tail end of the last jointed section of a wire by a method wherein high-pressure air is blasted on a gold wire located between a clamp and a wire spool.

CONSTITUTION: A capillary 11 and a pellet 16 are heated up, high-pressure air is blasted on the gold wire 12 from an air nozzle 15, a gold ball 12a is thermocompressed on the electrode of the pellet 16 using the capillary 11, and then the capillary 11 is moved to the side of a post 17 and the gold wire 12 is thermocompressed to the post 17 in the same manner. When the above bonding is finished, the gold wire 12 is picked up from the clamp 13, the tail end of the last joint section of the gold wire 12 is cut off and the bonding work is completed. As the high-pressure air is blasted on the gold wire, the generation of underloop is prevented and a stabilized bonding can be performed.

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